

**Amendments to the Claims**

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1. - 36. (Cancelled)

37. (Previously Presented) A clad board for forming circuitry, being manufactured by:

sticking a releasing film to a pre-preg sheet;

forming a hole in the pre-preg sheet with the releasing film, the hole being one of a non-through-hole and a through-hole;

filling the hole with conductive paste;

peeling off the releasing film; and

heating and pressing a metal foil onto the pre-preg sheet,

wherein said clad board comprises:

a fiber sheet included in the pre-preg sheet, the fiber sheet comprising a non-woven fabric and a resin material impregnated into the fiber sheet, the resin material comprising at least one of a thermoplastic resin and a thermosetting resin having a semi-cured portion, the fiber sheet having a top surface and a bottom surface; and

a resin layer formed smoothly on both the top surface and the bottom surface of the fiber sheet, the resin layer being made of material identical to the resin material; and

wherein the fiber sheet comprises:

an inside layer having two faces and two surface layers, one of which surface layers is disposed on each face of the inside layer;

wherein the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers; and

wherein the inside layer and the surface layers are made of materials identical to each other.

38. - 39. (Cancelled)

40. (Currently Amended) The clad board of claim 37, wherein the surface layers of the fiber sheet ~~has each have a~~ density ranging from 700 kg/m<sup>3</sup> to 1000 kg/m<sup>3</sup>.

41. - 58. (Cancelled)

59. (Previously Presented) The clad board of claim 37,

wherein the fiber sheet has a hole formed therein, said clad board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising non-spherical-shaped conductive particles.

60. - 75. (Cancelled)

76. (Currently Amended) A core board for a clad board for forming circuitry, comprising:

a fiber sheet;

the fiber sheet comprising a non-woven fabric and a resin material impregnated into the fiber sheet, the resin material including at least one of a thermoplastic resin and a thermoplastic resin having a semi-cured portion, the fiber sheet having a top surface and a bottom surface; and a resin layer formed on both the top surface and the bottom surface of the fiber sheet, being made of material identical to the resin material;

wherein the fiber sheet comprises:

an inside layer having two faces and two surface layers, one which surface layers is disposed on each face of the inside layer; and

~~first and second layers disposed at respective outermost sides of the fiber sheet;~~

wherein the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers; and

wherein the inside layer and the surface layers are made of materials identical to each other.

77. - 83. (Cancelled)

84. (Previously Presented) The core board of claim 76, wherein the fiber sheet has a hole formed therein, said core board further comprising a conductive paste filling the hole of the fiber sheet, the conductive paste comprising non-spherical-shaped conductive particles.

85. (Currently Amended) The core board of claim 76, wherein the surface layers of the fiber sheet ~~has~~ each have a density ranging from 700 kg/m<sup>3</sup> to 1000 kg/m<sup>3</sup>.

86. (Previously Presented) The clad board of claim 37, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

87. (Previously Presented) The core board of claim 76, wherein the resin material impregnated into the fiber sheet comprises the thermosetting resin having a semi-cured portion.

88. - 95. (Cancelled)

96. (Previously Presented) The clad board of claim 37, wherein the impregnated resin comprises 51 weight% to 54 weight% of the pre-preg sheet.

97. (Previously Presented) The core board of claim 76, wherein the impregnated resin comprises 51 weight% to 54 weight% of the pre-preg sheet.

98. (Previously Presented) The clad board of claim 37, wherein the non-woven fabric is an aramid fiber non-woven fabric.

99. (Currently Amended) The clad board of claim 98, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m<sup>3</sup> and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m<sup>3</sup>, subject to the proviso that the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers.

100. (Currently Amended) The clad board of claim 37, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m<sup>3</sup> and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m<sup>3</sup>, subject to the proviso that the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers.

101. (Previously Presented) The core board of claim 76, wherein the non-woven fabric is an aramid fiber non-woven fabric.

102. (Currently Amended) The core board of claim 101, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m<sup>3</sup> and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m<sup>3</sup>, subject to the proviso that the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers.

103. (Currently Amended) The core board of claim 76, wherein the density of the non-woven fabric in the inner layer is from 500 to 700 kg/m<sup>3</sup> and the density of the non-woven fabric in each of the surface layers is 700 to 1000 kg/m<sup>3</sup>, subject to the proviso that the density of the non-woven fabric in the inside layer is lower than the density of the non-woven fabric in each of the surface layers.

104. (Previously Presented) The clad board according to claim 37, wherein the inside layer and the two surface layers include a common resin material and a common non-woven fabric.

105. (Previously Presented) The clad board according to claim 37, wherein the fiber sheet includes a further inside layer, identical in material to the two surface layers, positioned between the inside layer and one of the two surface layers, and having a density lower than a density of either of the two surface layers.